

CAT93C46B

1-Kb Microwire Serial EEPROM



ON Semiconductor®

<http://onsemi.com>

Description

The CAT93C46B is a 1-Kb Serial EEPROM memory device which is configured as either 64 registers of 16 bits (ORG pin at V_{CC}) or 128 registers of 8 bits (ORG pin at GND). Each register can be written (or read) serially by using the DI (or DO) pin. The CAT93C46B features a self-timed internal write with auto-clear. On-chip Power-On Reset circuit protects the internal logic against powering up in the wrong state.

Features

- High Speed Operation: 4 MHz
- 1.8 V (1.65 V*) to 5.5 V Supply Voltage Range
- Selectable x8 or x16 Memory Organization
- Self-Timed Write Cycle with Auto-Clear
- Sequential Read
- Software Write Protection
- Power-up Inadvertant Write Protection
- Low Power CMOS Technology
- 1,000,000 Program/Erase Cycles
- 100 Year Data Retention
- Industrial and Extended Temperature Ranges
- 8-pin PDIP, SOIC, TSSOP and 8-pad UDFN and TDFN Packages
- This Device is Pb-Free, Halogen Free/BFR Free and RoHS Compliant†

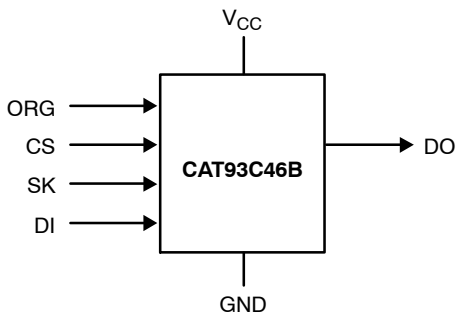
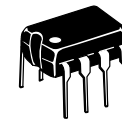


Figure 1. Functional Symbol

*CAT93C46Bxx-xxL (T_A = -20°C to +85°C)

†For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



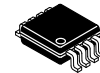
PDIP-8
L SUFFIX
CASE 646AA



TSSOP-8
Y SUFFIX
CASE 948AL



SOIC-8
V, W** SUFFIX
CASE 751BD



SOIC-8
X SUFFIX
CASE 751BE

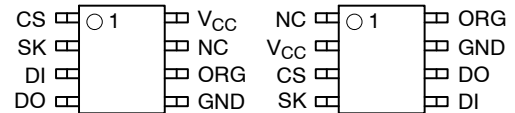


UDFN-8
HU4 SUFFIX
CASE 517AZ



TDFN-8**
VP2 SUFFIX
CASE 511AK

PIN CONFIGURATIONS



PDIP (L), SOIC (V, X),
TSSOP (Y), UDFN (HU4),
TDFN (VP2)**
(Top View)

SOIC (W)**
(Top View)

** Not recommended for new designs.

PIN FUNCTION

| Pin Name | Function |
|-----------------|---------------------|
| CS | Chip Select |
| SK | Clock Input |
| DI | Serial Data Input |
| DO | Serial Data Output |
| V _{CC} | Power Supply |
| GND | Ground |
| ORG | Memory Organization |
| NC | No Connection |

Note: When the ORG pin is connected to V_{CC}, the x16 organization is selected. When it is connected to ground, the x8 organization is selected. If the ORG pin is left unconnected, then an internal pullup device will select the x16 organization.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 14 of this data sheet.

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Table 1. ABSOLUTE MAXIMUM RATINGS

| Parameter | Value | Units |
|--|--------------|-------|
| Storage Temperature | -65 to +150 | °C |
| Voltage on Any Pin with Respect to Ground (Note 1) | -0.5 to +6.5 | V |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- The DC input voltage on any pin should not be lower than -0.5 V or higher than $V_{CC} + 0.5$ V. During transitions, the voltage on any pin may undershoot to no less than -1.5 V or overshoot to no more than $V_{CC} + 1.5$ V, for periods of less than 20 ns.

Table 2. RELIABILITY CHARACTERISTICS (Note 2)

| Symbol | Parameter | Min | Units |
|--------------------|----------------|-----------|------------------------|
| N_{END} (Note 3) | Endurance | 1,000,000 | Program / Erase Cycles |
| T_{DR} | Data Retention | 100 | Years |

- These parameters are tested initially and after a design or process change that affects the parameter according to appropriate AEC-Q100 and JEDEC test methods.
- Block Mode, $V_{CC} = 5$ V, 25°C

Table 3. D.C. OPERATING CHARACTERISTICS

($V_{CC} = +1.8$ V to +5.5 V, $T_A = -40$ °C to +125°C, $V_{CC} = +1.65$ V to +5.5 V, $T_A = -20$ °C to +85°C unless otherwise specified.)

| Symbol | Parameter | Test Conditions | Min | Max | Units |
|-----------|----------------------------|---|--------------------------|---------------------|-------|
| I_{CC1} | Supply Current (Write) | Write, $V_{CC} = 5.0$ V | | 1 | mA |
| I_{CC2} | Supply Current (Read) | Read, DO open, $f_{SK} = 2$ MHz, $V_{CC} = 5.0$ V | | 500 | μA |
| I_{SB1} | Standby Current (x8 Mode) | $V_{IN} = GND$ or V_{CC} $CS = GND$, $ORG = GND$ | $T_A = -40$ °C to +85°C | 2 | μA |
| | | | $T_A = -40$ °C to +125°C | 5 | |
| I_{SB2} | Standby Current (x16 Mode) | $V_{IN} = GND$ or V_{CC} $CS = GND$, $ORG = Float$ or V_{CC} | $T_A = -40$ °C to +85°C | 1 | μA |
| | | | $T_A = -40$ °C to +125°C | 3 | |
| I_{LI} | Input Leakage Current | $V_{IN} = GND$ to V_{CC} | $T_A = -40$ °C to +85°C | 1 | μA |
| | | | $T_A = -40$ °C to +125°C | 2 | |
| I_{LO} | Output Leakage Current | $V_{OUT} = GND$ to V_{CC} $CS = GND$ | $T_A = -40$ °C to +85°C | 1 | μA |
| | | | $T_A = -40$ °C to +125°C | 2 | |
| V_{IL1} | Input Low Voltage | 4.5 V $\leq V_{CC} < 5.5$ V | -0.1 | 0.8 | V |
| V_{IH1} | Input High Voltage | 4.5 V $\leq V_{CC} < 5.5$ V | 2 | $V_{CC} + 1$ | V |
| V_{IL2} | Input Low Voltage | 1.65 V $\leq V_{CC} < 4.5$ V | 0 | $V_{CC} \times 0.2$ | V |
| V_{IH2} | Input High Voltage | 1.65 V $\leq V_{CC} < 4.5$ V | $V_{CC} \times 0.7$ | $V_{CC} + 1$ | V |
| V_{OL1} | Output Low Voltage | 4.5 V $\leq V_{CC} < 5.5$ V, $I_{OL} = 3$ mA | | 0.4 | V |
| V_{OH1} | Output High Voltage | 4.5 V $\leq V_{CC} < 5.5$ V, $I_{OH} = -400$ μA | 2.4 | | V |
| V_{OL2} | Output Low Voltage | 1.65 V $\leq V_{CC} < 4.5$ V, $I_{OL} = 1$ mA | | 0.2 | V |
| V_{OH2} | Output High Voltage | 1.65 V $\leq V_{CC} < 4.5$ V, $I_{OH} = -100$ μA | $V_{CC} - 0.2$ | | V |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

Table 4. PIN CAPACITANCE ($T_A = 25$ °C, $f = 1$ MHz, $V_{CC} = 5$ V)

| Symbol | Test | Conditions | Min | Typ | Max | Units |
|--------------------|-------------------------------------|-----------------|-----|-----|-----|-------|
| C_{OUT} (Note 4) | Output Capacitance (DO) | $V_{OUT} = 0$ V | | | 5 | pF |
| C_{IN} (Note 4) | Input Capacitance (CS, SK, DI, ORG) | $V_{IN} = 0$ V | | | 5 | pF |

- These parameters are tested initially and after a design or process change that affects the parameter according to appropriate AEC-Q100 and JEDEC test methods.

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Table 5. A.C. CHARACTERISTICS

($V_{CC} = +1.8\text{ V to }+5.5\text{ V}$, $T_A = -40^\circ\text{C to }+125^\circ\text{C}$, $V_{CC} = +1.65\text{ V to }+5.5\text{ V}$, $T_A = -20^\circ\text{C to }+85^\circ\text{C}$ unless otherwise specified.)

| Symbol | Parameter | $V_{CC} < 3.3\text{ V}$ | | $V_{CC} > 3.3\text{ V}$ $T_A = -40^\circ\text{C to }+85^\circ\text{C}$ | | Units |
|-------------------|------------------------------|-------------------------|------|---|------|---------------|
| | | Min | Max | Min | Max | |
| t_{CSS} | CS Setup Time | 50 | | 50 | | ns |
| t_{CSH} | CS Hold Time | 0 | | 0 | | ns |
| t_{DIS} | DI Setup Time | 100 | | 50 | | ns |
| t_{DIH} | DI Hold Time | 100 | | 50 | | ns |
| t_{PD1} | Output Delay to 1 | | 0.25 | | 0.1 | μs |
| t_{PD0} | Output Delay to 0 | | 0.25 | | 0.1 | μs |
| t_{HZ} (Note 5) | Output Delay to High-Z | | 100 | | 100 | ns |
| t_{EW} | Program / Erase Cycle Time | WRITE, ERASE | 3 | | 3 | ms |
| | | WRAL, ERAL | 5 | | 5 | |
| t_{CSMIN} | Minimum CS Low Time | 0.25 | | 0.1 | | μs |
| t_{SKHI} | Minimum SK High Time | 0.25 | | 0.1 | | μs |
| t_{SKLOW} | Minimum SK Low Time | 0.25 | | 0.1 | | μs |
| t_{SV} | Output Delay to Status Valid | | 0.25 | | 0.1 | μs |
| SK_{MAX} | Maximum Clock Frequency | DC | 2000 | DC | 4000 | kHz |

5. This parameter is tested initially and after a design or process change that affects the parameter.

Table 6. POWER-UP TIMING (Notes 6 and 7)

| Symbol | Parameter | Max | Units |
|-----------|-----------------------------|-----|-------|
| t_{PUR} | Power-up to Read Operation | 0.1 | ms |
| t_{PUW} | Power-up to Write Operation | 0.1 | ms |

6. These parameters are tested initially and after a design or process change that affects the parameter according to appropriate AEC-Q100 and JEDEC test methods.

7. t_{PUR} and t_{PUW} are the delays required from the time V_{CC} is stable until the specified operation can be initiated.

Table 7. A.C. TEST CONDITIONS

| | | |
|---------------------------|--|---|
| Input Rise and Fall Times | $\leq 50\text{ ns}$ | |
| Input Pulse Voltages | 0.4 V to 2.4 V | $4.5\text{ V} \leq V_{CC} \leq 5.5\text{ V}$ |
| Timing Reference Voltages | 0.8 V, 2.0 V | $4.5\text{ V} \leq V_{CC} \leq 5.5\text{ V}$ |
| Input Pulse Voltages | $0.2 V_{CC}$ to $0.7 V_{CC}$ | $1.65\text{ V} \leq V_{CC} \leq 4.5\text{ V}$ |
| Timing Reference Voltages | $0.5 V_{CC}$ | $1.65\text{ V} \leq V_{CC} \leq 4.5\text{ V}$ |
| Output Load | Current Source I_{OLmax}/I_{OHmax} ; $C_L = 100\text{ pF}$ | |

CAT93C46B

Device Operation

The CAT93C46B is a 1024-bit nonvolatile memory intended for use with industry standard microprocessors. The CAT93C46B can be organized as either registers of 16 bits or 8 bits. When organized as X16, seven 9-bit instructions control the reading, writing and erase operations of the device. When organized as X8, seven 10-bit instructions control the reading, writing and erase operations of the device. The CAT93C46B operates on a single power supply and will generate on chip the high voltage required during any write operation.

Instructions, addresses, and write data are clocked into the DI pin on the rising edge of the clock (SK). The DO pin is normally in a high impedance state except when reading data from the device, or when checking the ready/busy status during a write operation. The serial communication protocol follows the timing shown in Figure 2.

The ready/busy status can be determined after the start of internal write cycle by selecting the device (CS high) and polling the DO pin; DO low indicates that the write operation is not completed, while DO high indicates that the device is ready for the next instruction. If necessary, the DO pin may be placed back into a high impedance state during chip select by shifting a dummy “1” into the DI pin. The DO pin will enter the high impedance state on the rising edge of the clock (SK). Placing the DO pin into the high impedance state is recommended in applications where the DI pin and the DO pin are to be tied together to form a common DI/O pin. The Ready/Busy flag can be disabled only in Ready state; no change is allowed in Busy state.

The format for all instructions sent to the device is a logical “1” start bit, a 2-bit (or 4-bit) opcode, 6-bit address (an additional bit when organized X8) and for write operations a 16-bit data field (8-bit for X8 organization).

Read

Upon receiving a READ command (Figure 3) and an address (clocked into the DI pin), the DO pin of the CAT93C46B will come out of the high impedance state and, after sending an initial dummy zero bit, will begin shifting out the data addressed (MSB first). The output data bits will toggle on the rising edge of the SK clock and are stable after the specified time delay (t_{PD0} or t_{PD1}).

After the initial data word has been shifted out and CS remains asserted with the SK clock continuing to toggle, the device will automatically increment to the next address and shift out the next data word in a sequential READ mode. As long as CS is continuously asserted and SK continues to toggle, the device will keep incrementing to the next address automatically until it reaches to the end of the address space, then loops back to address 0. In the sequential READ mode, only the initial data word is preceded by a dummy zero bit. All subsequent data words will follow without a dummy zero bit.

Erase/Write Enable and Disable

The CAT93C46B powers up in the write disable state. Any writing after power-up or after an EWDS (write disable) instruction must first be preceded by the EWEN (write enable) instruction. Once the write instruction is enabled, it will remain enabled until power to the device is removed, or the EWDS instruction is sent. The EWDS instruction can be used to disable all CAT93C46B write and erase instructions, and will prevent any accidental writing or clearing of the device. Data can be read normally from the device regardless of the write enable/disable status. The EWEN and EWDS instructions timing is shown in Figure 4.

Table 8. INSTRUCTION SET

| Instruction | Start Bit | Opcode | Address | | Data | | Comments |
|-------------|-----------|--------|---------|--------|-------|--------|---------------------|
| | | | x8 | x16 | x8 | x16 | |
| READ | 1 | 10 | A6-A0 | A5-A0 | | | Read Address AN-A0 |
| ERASE | 1 | 11 | A6-A0 | A5-A0 | | | Clear Address AN-A0 |
| WRITE | 1 | 01 | A6-A0 | A5-A0 | D7-D0 | D15-D0 | Write Address AN-A0 |
| EWEN | 1 | 00 | 11XXXXX | 11XXXX | | | Write Enable |
| EWDS | 1 | 00 | 00XXXXX | 00XXXX | | | Write Disable |
| ERAL* | 1 | 00 | 10XXXXX | 10XXXX | | | Clear All Addresses |
| WRAL* | 1 | 00 | 01XXXXX | 01XXXX | D7-D0 | D15-D0 | Write All Addresses |

* Not available at $V_{CC} < 1.8 V$

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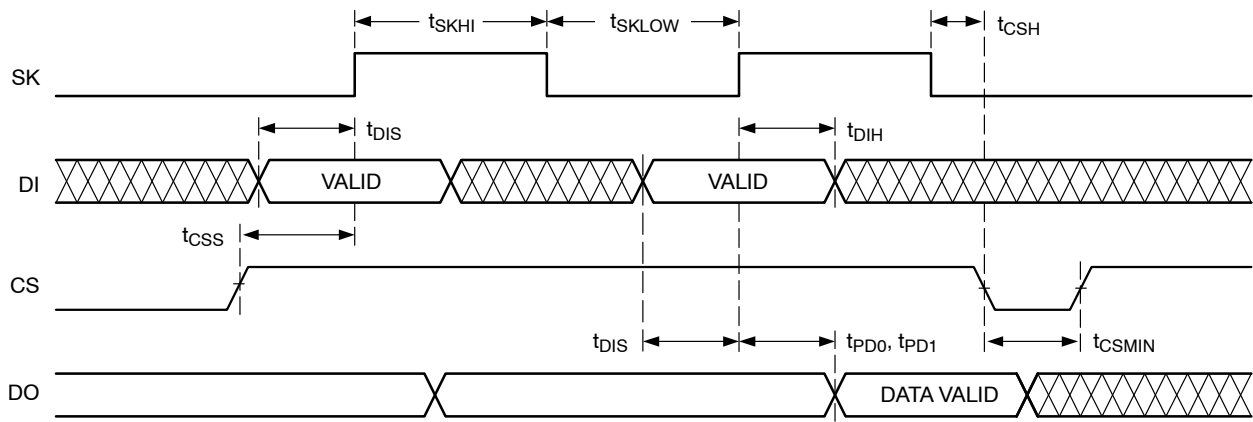


Figure 2. Synchronous Data Timing

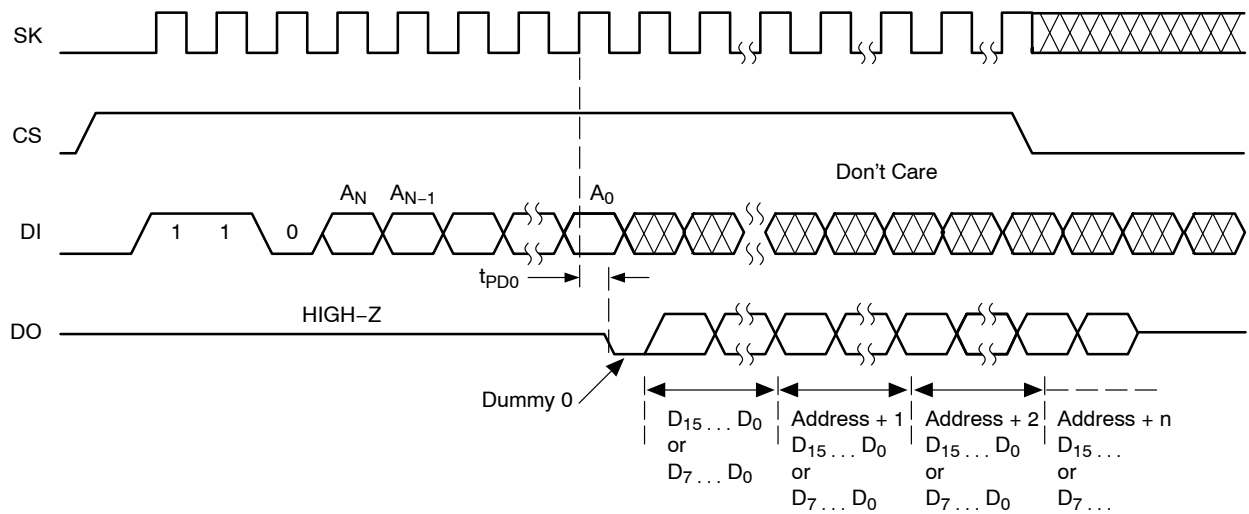


Figure 3. Read Instruction Timing

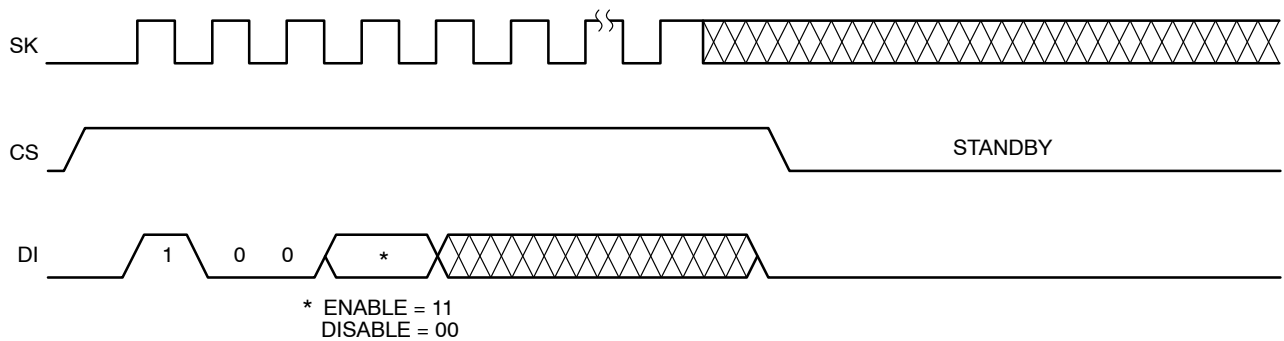


Figure 4. EWEN/EWDS Instruction Timing

CAT93C46B

Write

After receiving a WRITE command (Figure 5), address and the data, the CS (Chip Select) pin must be deselected for a minimum of t_{CSMIN} . The falling edge of CS will start the self clocking for auto-clear and data store cycles on the memory location specified in the instruction. The clocking of the SK pin is not necessary after the device has entered the self clocking mode. The ready/busy status of the CAT93C46B can be determined by selecting the device and polling the DO pin. Since this device features Auto-Clear before write, it is NOT necessary to erase a memory location before it is written into.

Erase

Upon receiving an ERASE command and address, the CS (Chip Select) pin must be de-asserted for a minimum of t_{CSMIN} (Figure 6). The falling edge of CS will start the self clocking clear cycle of the selected memory location. The clocking of the SK pin is not necessary after the device has entered the self clocking mode. The ready/busy status of the CAT93C46B can be determined by selecting the device and polling the DO pin. Once cleared, the content of a cleared location returns to a logical "1" state.

Erase All

Upon receiving an ERAL command (Figure 7), the CS (Chip Select) pin must be deselected for a minimum of t_{CSMIN} . The falling edge of CS will start the self clocking clear cycle of all memory locations in the device. The clocking of the SK pin is not necessary after the device has entered the self clocking mode. The ready/busy status of the CAT93C46B can be determined by selecting the device and polling the DO pin. Once cleared, the contents of all memory bits return to a logical "1" state.

Write All

Upon receiving a WRAL command and data, the CS (Chip Select) pin must be deselected for a minimum of t_{CSMIN} (Figure 8). The falling edge of CS will start the self clocking data write to all memory locations in the device. The clocking of the SK pin is not necessary after the device has entered the self clocking mode. The ready/busy status of the CAT93C46B can be determined by selecting the device and polling the DO pin. It is not necessary for all memory locations to be cleared before the WRAL command is executed.

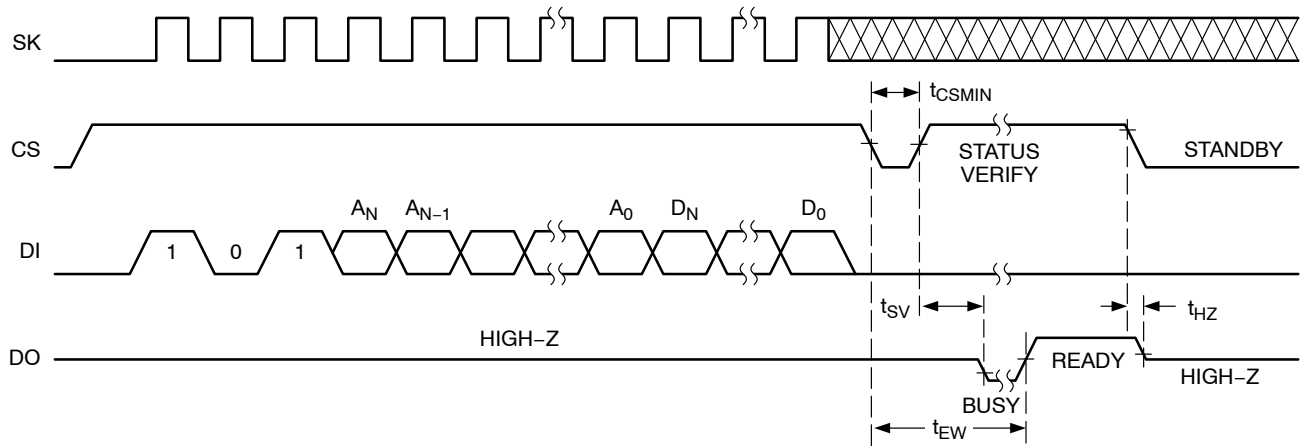


Figure 5. Write Instruction Timing

CAT93C46B

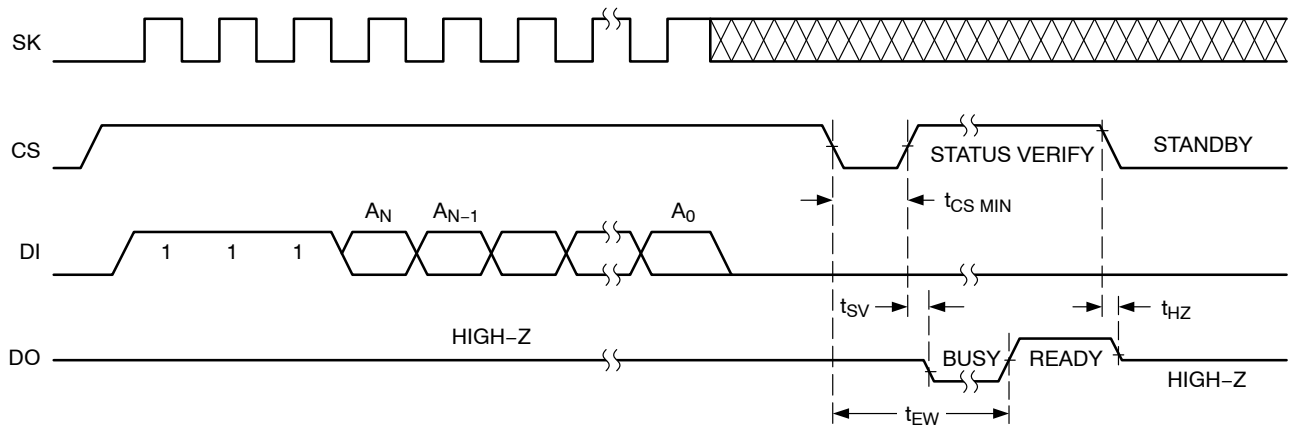


Figure 6. Erase Instruction Timing

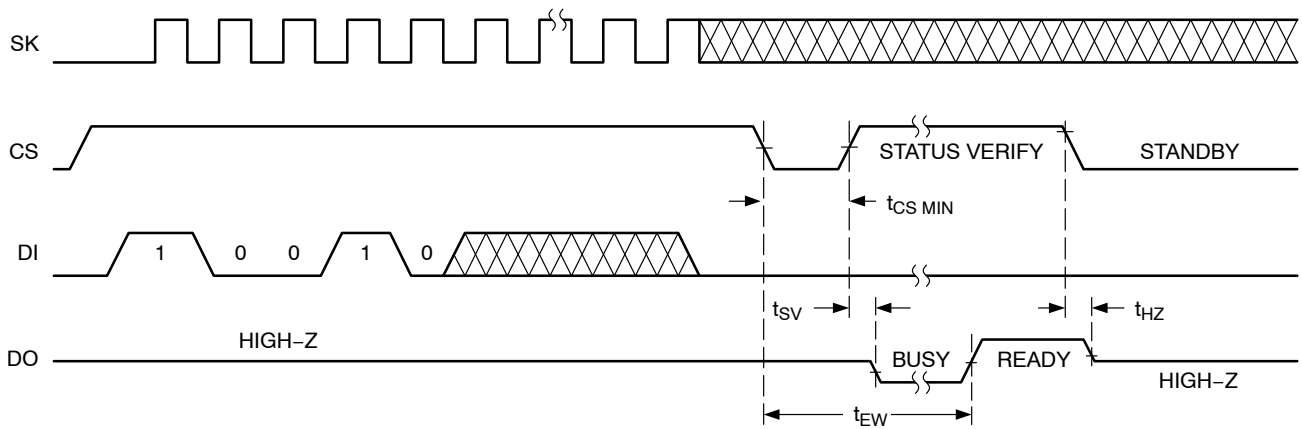


Figure 7. ERAL Instruction Timing

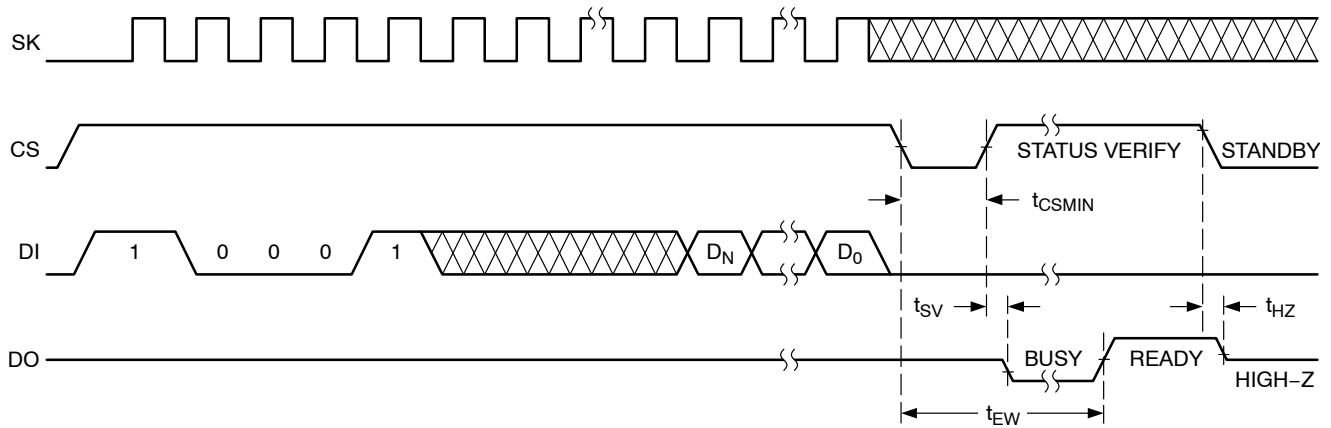
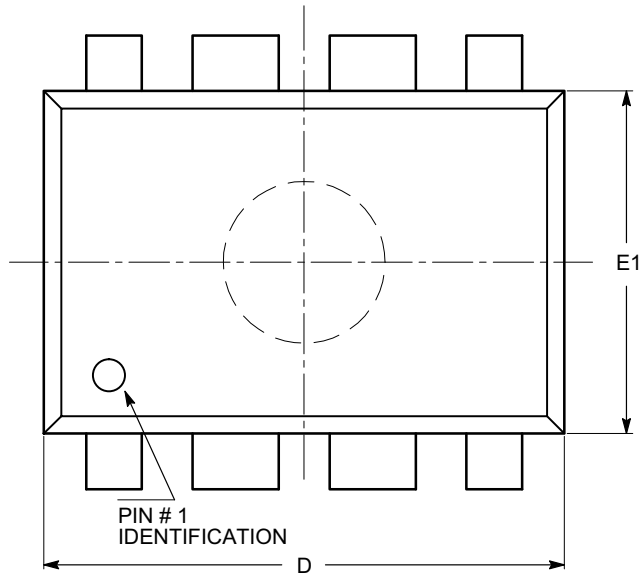


Figure 8. WRAL Instruction Timing

CAT93C46B

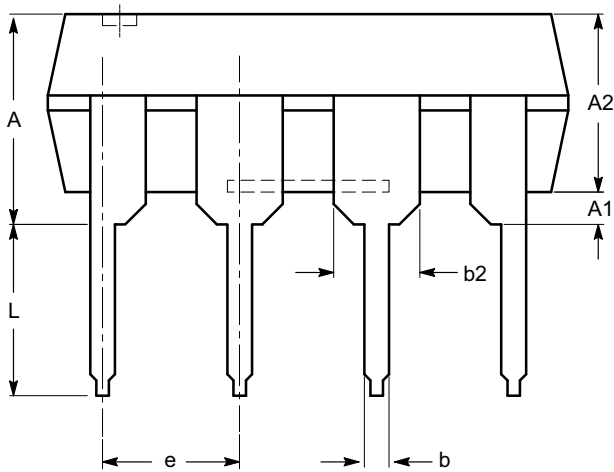
PACKAGE DIMENSIONS

PDIP-8, 300 mils
CASE 646AA-01
ISSUE A

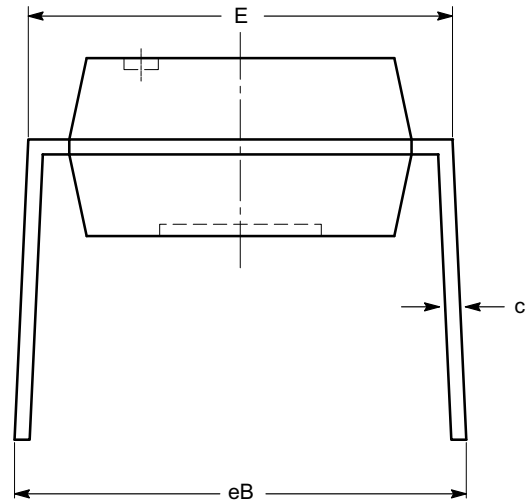


| SYMBOL | MIN | NOM | MAX |
|--------|----------|------|-------|
| A | | | 5.33 |
| A1 | 0.38 | | |
| A2 | 2.92 | 3.30 | 4.95 |
| b | 0.36 | 0.46 | 0.56 |
| b2 | 1.14 | 1.52 | 1.78 |
| c | 0.20 | 0.25 | 0.36 |
| D | 9.02 | 9.27 | 10.16 |
| E | 7.62 | 7.87 | 8.25 |
| E1 | 6.10 | 6.35 | 7.11 |
| e | 2.54 BSC | | |
| eB | 7.87 | | 10.92 |
| L | 2.92 | 3.30 | 3.80 |

TOP VIEW



SIDE VIEW



END VIEW

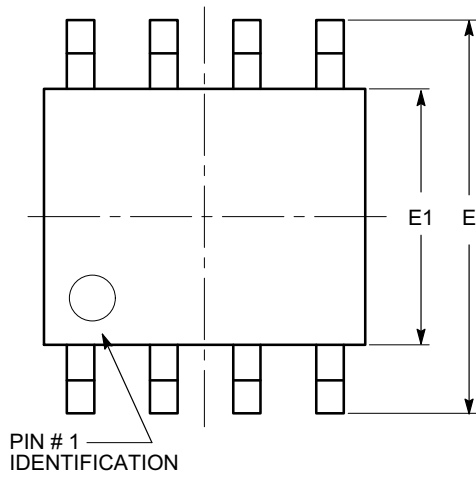
Notes:

- (1) All dimensions are in millimeters.
- (2) Complies with JEDEC MS-001.

CAT93C46B

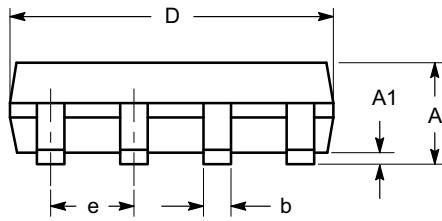
PACKAGE DIMENSIONS

SOIC 8, 150 mils
CASE 751BD-01
ISSUE O

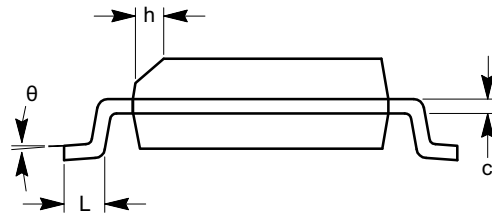


TOP VIEW

| SYMBOL | MIN | NOM | MAX |
|----------|----------|-----|------|
| A | 1.35 | | 1.75 |
| A1 | 0.10 | | 0.25 |
| b | 0.33 | | 0.51 |
| c | 0.19 | | 0.25 |
| D | 4.80 | | 5.00 |
| E | 5.80 | | 6.20 |
| E1 | 3.80 | | 4.00 |
| e | 1.27 BSC | | |
| h | 0.25 | | 0.50 |
| L | 0.40 | | 1.27 |
| θ | 0° | | 8° |



SIDE VIEW



END VIEW

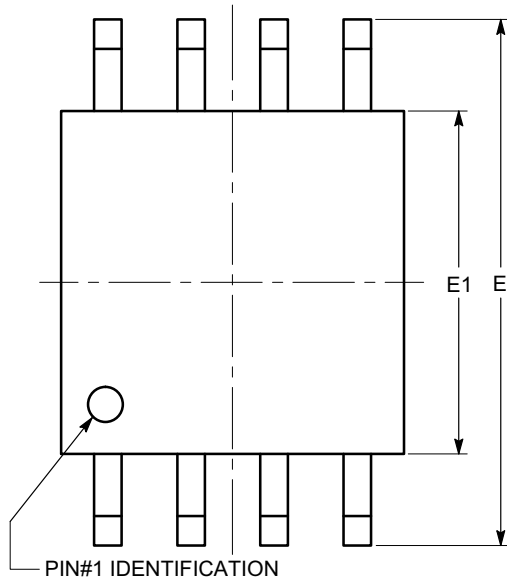
Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MS-012.

CAT93C46B

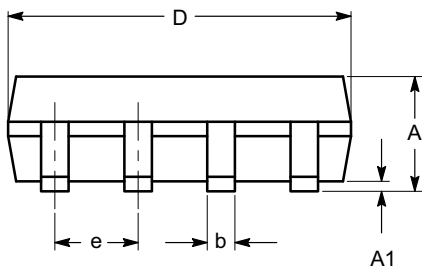
PACKAGE DIMENSIONS

SOIC-8, 208 mils
CASE 751BE-01
ISSUE O

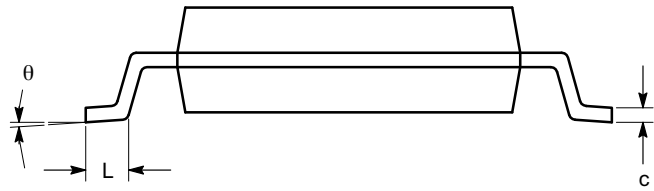


| SYMBOL | MIN | NOM | MAX |
|----------|----------|-----|------|
| A | | | 2.03 |
| A1 | 0.05 | | 0.25 |
| b | 0.36 | | 0.48 |
| c | 0.19 | | 0.25 |
| D | 5.13 | | 5.33 |
| E | 7.75 | | 8.26 |
| E1 | 5.13 | | 5.38 |
| e | 1.27 BSC | | |
| L | 0.51 | | 0.76 |
| θ | 0° | | 8° |

TOP VIEW



SIDE VIEW



END VIEW

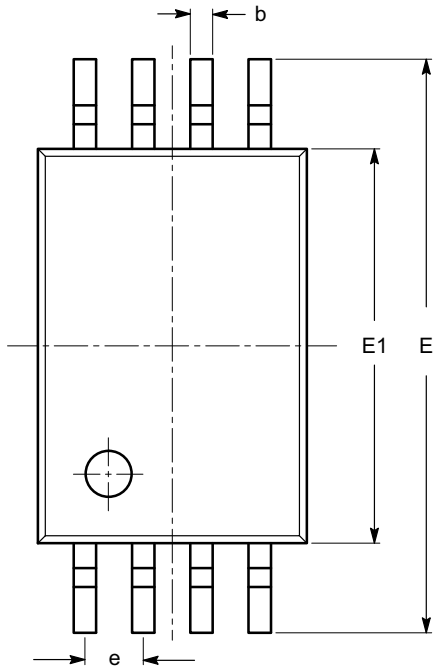
Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with EIAJ EDR-7320.

CAT93C46B

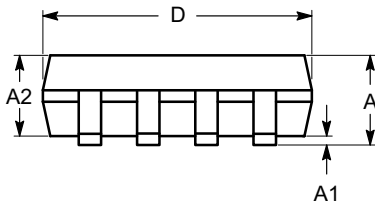
PACKAGE DIMENSIONS

TSSOP8, 4.4x3
CASE 948AL-01
ISSUE O

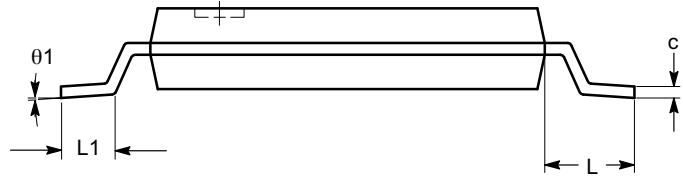


| SYMBOL | MIN | NOM | MAX |
|----------|----------|------|------|
| A | | | 1.20 |
| A1 | 0.05 | | 0.15 |
| A2 | 0.80 | 0.90 | 1.05 |
| b | 0.19 | | 0.30 |
| c | 0.09 | | 0.20 |
| D | 2.90 | 3.00 | 3.10 |
| E | 6.30 | 6.40 | 6.50 |
| E1 | 4.30 | 4.40 | 4.50 |
| e | 0.65 BSC | | |
| L | 1.00 REF | | |
| L1 | 0.50 | 0.60 | 0.75 |
| θ | 0° | | 8° |

TOP VIEW



SIDE VIEW



END VIEW

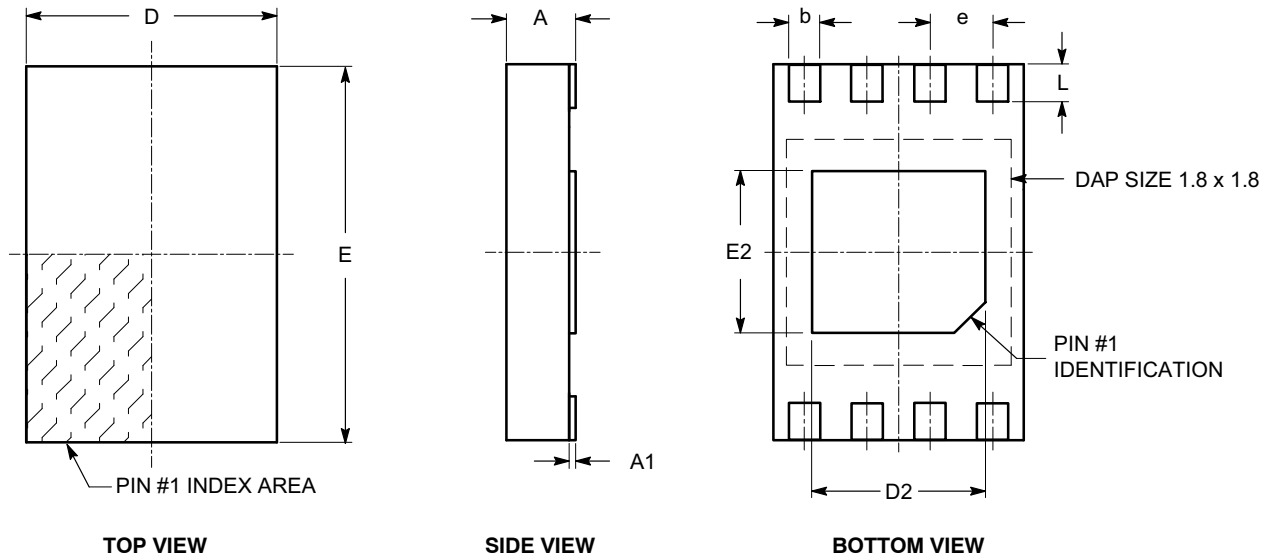
Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MO-153.

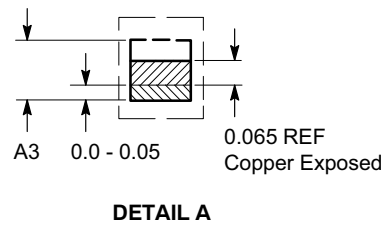
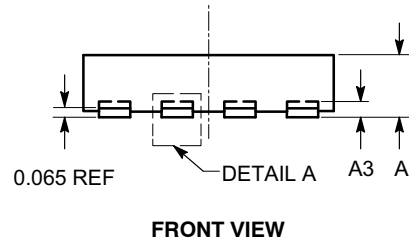
CAT93C46B

PACKAGE DIMENSIONS

UDFN8, 2x3 EXTENDED PAD
CASE 517AZ-01
ISSUE O



| SYMBOL | MIN | NOM | MAX |
|--------|-----------|------|------|
| A | 0.45 | 0.50 | 0.55 |
| A1 | 0.00 | 0.02 | 0.05 |
| A3 | 0.127 REF | | |
| b | 0.20 | 0.25 | 0.30 |
| D | 1.95 | 2.00 | 2.05 |
| D2 | 1.35 | 1.40 | 1.45 |
| E | 2.95 | 3.00 | 3.05 |
| E2 | 1.25 | 1.30 | 1.35 |
| e | 0.50 REF | | |
| L | 0.25 | 0.30 | 0.35 |



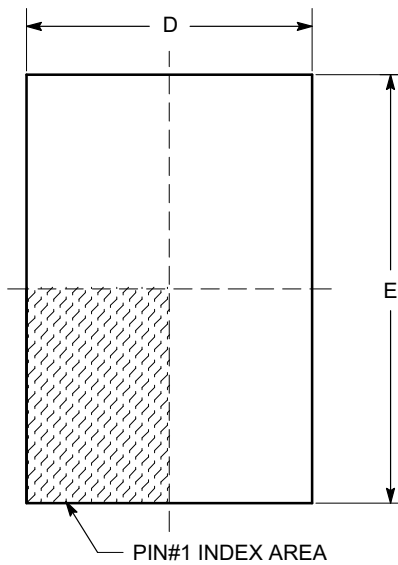
Notes:

- (1) All dimensions are in millimeters.
- (2) Refer JEDEC MO-236/MO-252.

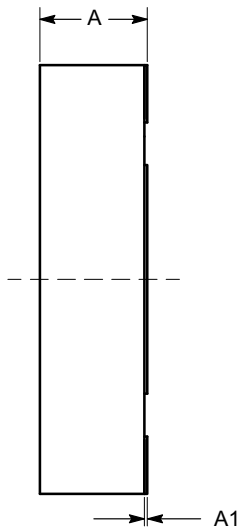
CAT93C46B

PACKAGE DIMENSIONS

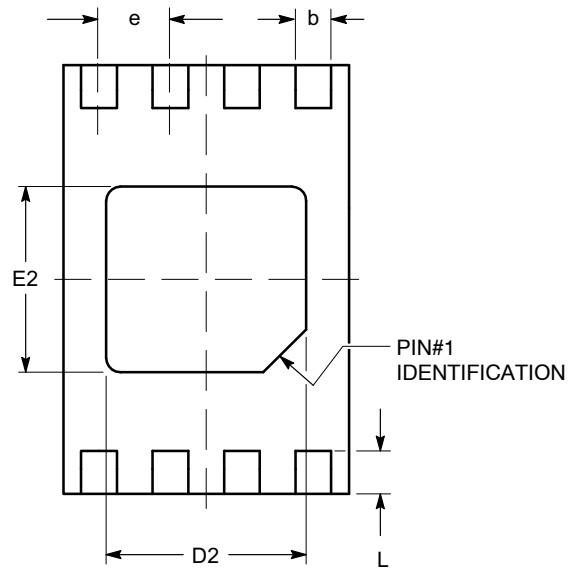
TDFN8, 2x3
CASE 511AK-01
ISSUE A



TOP VIEW

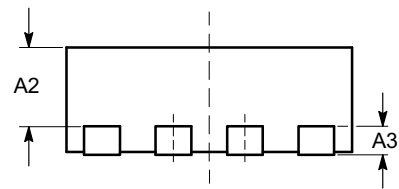


SIDE VIEW



BOTTOM VIEW

| SYMBOL | MIN | NOM | MAX |
|--------|----------|------|------|
| A | 0.70 | 0.75 | 0.80 |
| A1 | 0.00 | 0.02 | 0.05 |
| A2 | 0.45 | 0.55 | 0.65 |
| A3 | 0.20 REF | | |
| b | 0.20 | 0.25 | 0.30 |
| D | 1.90 | 2.00 | 2.10 |
| D2 | 1.30 | 1.40 | 1.50 |
| E | 2.90 | 3.00 | 3.10 |
| E2 | 1.20 | 1.30 | 1.40 |
| e | 0.50 TYP | | |
| L | 0.20 | 0.30 | 0.40 |



FRONT VIEW

Notes:


- (1) All dimensions are in millimeters.
- (2) Complies with JEDEC MO-229.

CAT93C46B

Example of Ordering Information

| Device Order Number | Specific Device Marking | Package Type | Temperature Range | Lead Finish | Shipping |
|-------------------------------|-------------------------|---------------|------------------------------------|-------------|------------------------------------|
| CAT93C46BLI-G | 93C46P | PDIP-8 | I = Industrial (-40°C to +85°C) | NiPdAu | Tube, 50 Units / Tube |
| CAT93C46BLE-G | 93C46P | PDIP-8 | E = Extended (-40°C to +125°C) | NiPdAu | Tube, 50 Units / Tube |
| CAT93C46BVE-GT3 | 93C46P | SOIC-8, JEDEC | E = Extended (-40°C to +125°C) | NiPdAu | Tape & Reel, 3,000 Units / Reel |
| CAT93C46BVI-GT3 | 93C46P | SOIC-8, JEDEC | I = Industrial (-40°C to +85°C) | NiPdAu | Tape & Reel, 3,000 Units / Reel |
| CAT93C46BVI-GT3L | 93C46P | SOIC-8, JEDEC | I = Industrial (-20°C to +85°C) | NiPdAu | Tape & Reel, 3,000 Units / Reel |
| CAT93C46BVP2I-GT3 (Note 8) | M0T | TDFN-8 | I = Industrial (-40°C to +85°C) | NiPdAu | Tape & Reel, 3,000 Units / Reel |
| CAT93C46BWI-GT3 (Note 8) | 93C46P | SOIC-8, JEDEC | I = Industrial (-40°C to +85°C) | NiPdAu | Tape & Reel, 3,000 Units / Reel |
| CAT93C46BXI-T2 | 93C46P | SOIC-8, EIAJ | I = Industrial (-40°C to +85°C) | Matte-Tin | Tape & Reel, 2,000 Units / Reel |
| CAT93C46BXE-T2 | 93C46P | SOIC-8, EIAJ | E = Extended (-40°C to +125°C) | Matte-Tin | Tape & Reel, 2,000 Units / Reel |
| CAT93C46BYI-GT3 | M46P | TSSOP-8 | I = Industrial (-40°C to +85°C) | NiPdAu | Tape & Reel, 3,000 Units / Reel |
| CAT93C46BYI-GT3L | M46P | TSSOP-8 | I = Industrial (-20°C to +85°C) | NiPdAu | Tape & Reel, 3,000 Units / Reel |
| CAT93C46BYE-GT3 | M46P | TSSOP-8 | E = Extended (-40°C to +125°C) | NiPdAu | Tape & Reel, 3,000 Units / Reel |
| CAT93C46BHU4I-GT3 | M0U | UDFN-8 | I = Industrial (-40°C to +85°C) | NiPdAu | Tape & Reel, 3,000 Units / Reel |
| CAT93C46BHU4E-GT3 | M0U | UDFN-8 | E = Extended (-40°C to +125°C) | NiPdAu | Tape & Reel, 3,000 Units / Reel |

8. Not recommended for new designs.
9. All packages are RoHS-compliant (Lead-free, Halogen-free).
10. **The standard lead finish is NiPdAu.**
11. For additional package and temperature options, please contact your nearest ON Semiconductor Sales office.
12. For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
13. For detailed information and a breakdown of device nomenclature and numbering systems, please see the ON Semiconductor Device Nomenclature document, TND310/D, available at www.onsemi.com

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